

Moisture Sensitivity Level (MSL)

- J-STD-020D: Moisture/Reflow Classification for Non-hermetic Solid State Surface Mount Devices)
 - applicable to non-hermetic surface mount devices, specifically those in plastic packages
- A plastic package contains moisture, which can become high pressure vapor during reflow, potentially resulting in internal cracking or damage to the device. It can also result in external steam jets from the package, which may displace other nearby components on the circuit board during the solder process. A common industry reference for this is "popcorning".

- Products have been requalified to new higher soldering temperatures.
- No degradation in MSL ratings observed.
- If pressed for MSL on ceramic chips, the level would be 1.

Product Type		MSL
Ceramic MLCC Chip		n/a
Tantalum MnO ₂		1
KO-CAP Polymer, AO CAP Aluminum		3
Ceramic Conformally Coated Axials and Radials		1
Ceramic Commercial Molded Axials and Radials		1
Tantalum Through Hole		1